

SOT1185-1

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | Q (quad) |
| Package type descriptive code | HVQFN32 |
| Package type industry code | HVQFN32 |
| Package style descriptive code | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | --- |
| JEDEC package outline code | --- |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 9-8-2010 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|------|-----|------|
| D | package length | 2.9 | - | 3 | 3.1 | mm |
| E | package width | 5.9 | - | 6 | 6.1 | mm |
| A | seated height | 0.8 | - | 0.85 | 1 | mm |
| e | nominal pitch | - | - | 0.4 | - | mm |
| n ₂ | actual quantity of termination | - | - | 32 | - | |

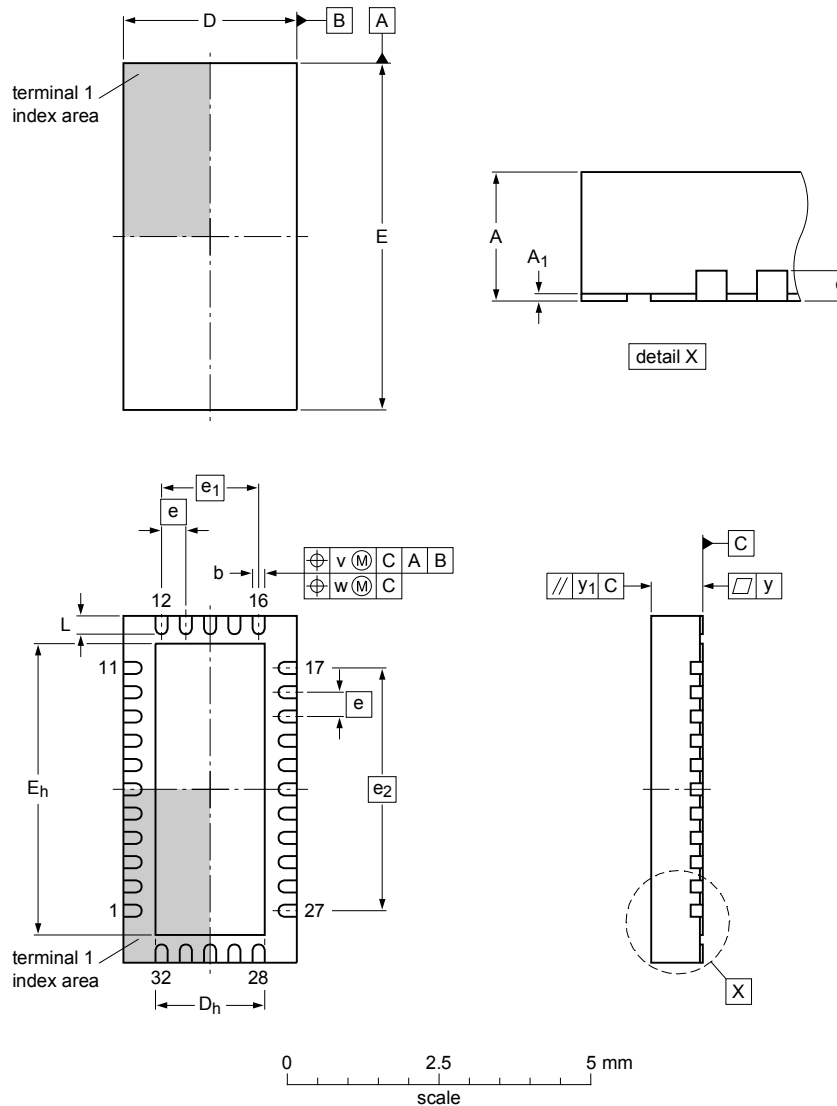


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2. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; 3 x 6 x 0.85 mm

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Dimensions

| Unit | A ⁽¹⁾ | A ₁ | b | c | D ⁽¹⁾ | D _h | E ⁽¹⁾ | E _h | e | e ₁ | e ₂ | L | v | w | y | y ₁ |
|------|------------------|----------------|------|-----|------------------|----------------|------------------|----------------|-----|----------------|----------------|-----|------|------|------|----------------|
| mm | max 1.00 | 0.05 | 0.25 | | 3.1 | 1.9 | 6.1 | 4.9 | | | | 0.4 | | | | |
| | nom 0.85 | 0.02 | 0.20 | 0.2 | 3.0 | 1.8 | 6.0 | 4.8 | 0.4 | 1.6 | 4 | 0.3 | 0.07 | 0.05 | 0.08 | 0.1 |
| | min 0.80 | 0.00 | 0.15 | | 2.9 | 1.7 | 5.9 | 4.7 | | | | 0.2 | | | | |

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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| Outline version | References | | | European projection | Issue date |
|-----------------|------------|-------|-------|---------------------|---------------------------------|
| | IEC | JEDEC | JEITA | | |
| SOT1185-1 | --- | --- | --- | | 10-07-26 10-08-09 |

Fig. 1. Package outline HVQFN32 (SOT1185-1)

3. Legal information

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